

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

1 - 13. (Canceled)

1                   14.     (Currently amended): A method of inspecting particles or defects  
2 comprising the steps of:  
3                   irradiating an object under inspection with light;  
4                   detecting reflected light or scattered light from the object under inspection;  
5                   detecting particles or defects based on a signal indicative of detected reflected  
6 light or scattered light;  
7                   processing the signal indicative of detected reflected light or scattered light to  
8 measure a size of each particle or defect;  
9                   processing data including the signal indicative of detected reflected light or  
10 scattered light, and a result of measuring the size of each particle or defect; and  
11                   displaying the result of data processing,  
12                   wherein ~~said~~ the step of processing data includes dividing the object under  
13 inspection into several regions, and processing data for each of the regions;  
14                   wherein the step of displaying includes presenting a graphical indication of a size  
15 distribution of the particles or defects in each of the regions.

1                   15.     (Original): A method of inspecting particles or defects according to claim  
2 14, wherein said step of displaying includes displaying particles or defects having a particular  
3 size in a manner discriminative from the remaining particles or defects for each of the regions.

1                   16.     (Original): A method of inspecting particles or defects according to claim  
2 14, wherein said step of displaying includes displaying a distribution of frequencies for the  
3 particle or defect sizes in each of the regions.

17 - 20. (Canceled)

1                   21. (Previously presented): A method as in claim 14 further comprising  
2 displaying a distribution of frequencies for particle or defect sizes measured.

1                   22. (Previously presented): A method as in claim 14 further comprising  
2 displaying particles or defects having a particular size in a manner to discriminate particles or  
3 defects of that particular size from particles or defects of other sizes.

1                   23. (New): A method as in claim 14, wherein the object is a semiconductor  
2 wafer on which a plurality of dies are formed, and the regions are divided according to a plurality  
3 of circuit pattern densities formed on the dies.

1                   24. (New): A method as in claim 23 wherein for each die, each of the circuit  
2 pattern densities differs from one another, and each of regions respectively correspond to one of  
3 the circuit pattern densities, a minimum size of particles or defect in each of the regions being  
4 different from one another.